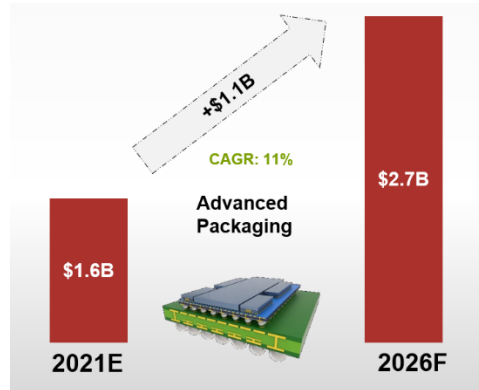


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PVD Wafer
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ASMPT NEXX, Inc. is a leading supplier of Advanced Packaging deposition equipment for the semiconductor industry, providing sputtering (PVD) and electroplating (ECD) tools to customers worldwide.

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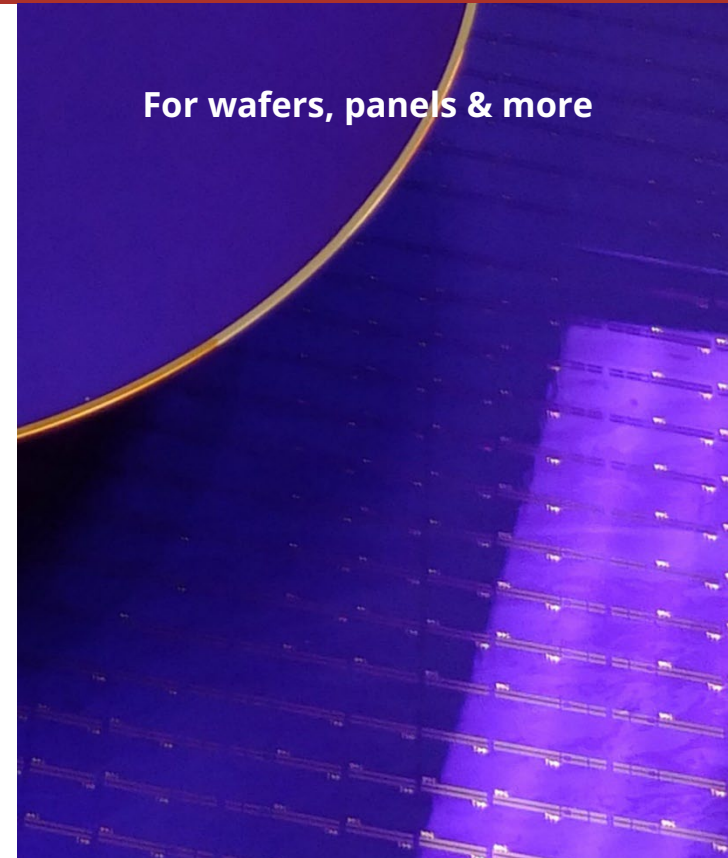
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For wafers, panels & more



Physical Vapor Deposition

Electro-chemical Deposition

Electro-chemical Deposition

Apollo

Wafer Level



Stratus™

Wafer Level



P500

Panel Level



More flexible features

- Highest flexibility sputtering tool on the market in the smallest footprint
- Bridge capability for 100, 150, 200 & 300 mm wafers as well as package level
- Configurable for up to 5 metal targets
- Safe wafer handling for various fragile substrates, thin and bowed wafer types

Safer substrate handling

- Highest flexibility plating tool on the market
- Bridge capability for 100, 150 & 200 mm or 200 & 300 mm wafers
- Processes up to 6 chemistries at one time
- Safe wafer handling for various fragile substrates, thin and bowed wafer types

Higher precision technology

- Highest wafer scale precision solution on the market for panels
- Handles panel sizes up to 510 x 515 mm
- Processes up to 5 chemistries at one time
- Safe substrate and glass panel handling

With more applications...

- Under bump metallization for bumping and redistribution layers
- Interposers, fan out and TSV
- RF Filter wafer level chip scale processing
- Power Devices (FSM & BSM)

ASMP enabling the digital world

- Wafer bumping (RDL, Cu Pillar, Microbump and Au)
- Interposers, fan out and TSV
- RF Filter wafer level chip scale processing
- Power Devices (FSM & BSM)

The right choice for you and your customers

- Fan out panel scale plating
- Embedded interconnections in substrate